



October 1998
Revised February 2005

74LVTH125

Low Voltage Quad Buffer with 3-STATE Outputs

General Description

The LVTH125 contains four independent non-inverting buffers with 3-STATE outputs.

These buffers are designed for low-voltage (3.3V) V_{CC} applications, but with the capability to provide a TTL interface to a 5V environment. The LVTH125 is fabricated with an advanced BiCMOS technology to achieve high speed operation similar to 5V ABT while maintaining a low power dissipation.

Features

- Input and output interface capability to systems at 5V V_{CC}
- Bushold data inputs eliminate the need for external pull-up resistors to hold unused inputs
- Live insertion/extraction permitted
- Power Up/Down high impedance provides glitch-free bus loading
- Outputs source/sink -32 mA/+64 mA
- Functionally compatible with the 74 series 125
- Latch-up performance exceeds 500 mA
- ESD performance:
 Human-body model > 2000V
 Machine model > 200V
 Charged-device model > 1000V

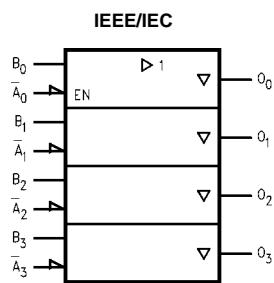
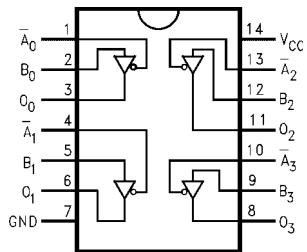
Ordering Code:

Order Number	Package Number	Package Description
74LVTH125M	M14A	14-Lead Small Outline Integrated Circuit (SOIC), JEDEC MS-012, 0.150" Narrow
74LVTH125SJ	M14D	Pb-Free 14-Lead Small Outline Package (SOP), EIAJ TYPE II, 5.3mm Wide
74LVTH125MTC	MTC14	14-Lead Thin Shrink Small Outline Package (TSSOP), JEDEC MO-153, 4.4mm Wide
74LVTH125MTCX_NL (Note 1)	MTC14	Pb-Free 14-Lead Thin Shrink Small Outline Package (TSSOP), JEDEC MO-153, 4.4mm Wide

Device also available in Tape and Reel. Specify by appending suffix letter "X" to the ordering code.

Pb-Free package per JEDEC J-STD-020B.

Note 1: "_NL" indicates Pb-Free package (per JEDED J-STD-020B). Device available in Tape and Reel only.

Logic Symbol**Connection Diagram****Truth Table**

Inputs		Output
\bar{A}_n	B_n	O_n
L	L	L
L	H	H
H	X	Z

H = HIGH Voltage Level
 L = LOW Voltage Level
 X = Immaterial
 Z = HIGH Impedance

Pin Descriptions

Pin Names	Description
\bar{A}_n, B_n	Inputs
O_n	3-STATE Outputs

Absolute Maximum Ratings (Note 2)

Symbol	Parameter	Value	Conditions	Units
V _{CC}	Supply Voltage	-0.5 to +4.6		V
V _I	DC Input Voltage	-0.5 to +7.0		V
V _O	DC Output Voltage	-0.5 to +7.0	Output in 3-STATE	V
		-0.5 to +7.0	Output in HIGH or LOW State (Note 3)	
I _{IK}	DC Input Diode Current	-50	V _I < GND	mA
I _{OK}	DC Output Diode Current	-50	V _O < GND	mA
I _O	DC Output Current	64	V _O > V _{CC} Output at HIGH State	mA
		128	V _O > V _{CC} Output at LOW State	
I _{CC}	DC Supply Current per Supply Pin	±64		mA
I _{GND}	DC Ground Current per Ground Pin	±128		mA
T _{STG}	Storage Temperature	-65 to +150		°C

Recommended Operating Conditions

Symbol	Parameter	Min	Max	Units
V _{CC}	Supply Voltage	2.7	3.6	V
V _I	Input Voltage	0	5.5	V
I _{OH}	HIGH Level Output Current		-32	mA
I _{OL}	LOW Level Output Current		64	mA
T _A	Free-Air Operating Temperature	-40	85	°C
Δt/ΔV	Input Edge Rate, V _{IN} = 0.8V – 2.0V, V _{CC} = 3.0V	0	10	ns/V

Note 2: Absolute Maximum continuous ratings are those values beyond which damage to the device may occur. Exposure to these conditions or conditions beyond those indicated may adversely affect device reliability. Functional operation under absolute maximum rated conditions is not implied.

Note 3: I_O Absolute Maximum Rating must be observed.

DC Electrical Characteristics

Symbol	Parameter	V_{CC} (V)	$T_A = -40^\circ C \text{ to } +85^\circ C$			Units	Conditions
			Min	Typ (Note 4)	Max		
V_{IK}	Input Clamp Diode Voltage	2.7			-1.2	V	$I_I = -18 \text{ mA}$
V_{IH}	Input HIGH Voltage	2.7–3.6	2.0			V	$V_O \leq 0.1V$ or $V_O \geq V_{CC} - 0.1V$
V_{IL}	Input LOW Voltage	2.7–3.6			0.8	V	
V_{OH}	Output HIGH Voltage	2.7–3.6	$V_{CC} - 0.2$			V	$I_{OH} = -100 \mu A$
		2.7	2.4				$I_{OH} = -8 \text{ mA}$
		3.0	2.0				$I_{OH} = -32 \text{ mA}$
V_{OL}	Output LOW Voltage	2.7			0.2	V	$I_{OL} = 100 \mu A$
		2.7			0.5		$I_{OL} = 24 \text{ mA}$
		3.0			0.4		$I_{OL} = 16 \text{ mA}$
		3.0			0.5		$I_{OL} = 32 \text{ mA}$
		3.0			0.55		$I_{OL} = 64 \text{ mA}$
$I_{I(HOLD)}$	Bushold Input Minimum Drive	3.0	75			μA	$V_I = 0.8V$
			-75				$V_I = 2.0V$
$I_{I(OD)}$	Bushold Input Over-Drive Current to Change State	3.0	500			μA	(Note 5)
			-500				(Note 6)
I_I	Input Current	3.6			10	μA	$V_I = 5.5V$
		3.6			±1		$V_I = 0V \text{ or } V_{CC}$
		3.6			-5		$V_I = 0V$
		3.6			1		$V_I = V_{CC}$
I_{OFF}	Power Off Leakage Current	0			±100	μA	$0V \leq V_I \text{ or } V_O \leq 5.5V$
$I_{PU/PD}$	Power up/down 3-STATE Output Current	0–1.5V			±100	μA	$V_O = 0.5V \text{ to } 3.0V$ $V_I = GND \text{ or } V_{CC}$
I_{OZL}	3-STATE Output Leakage Current	3.6			-5	μA	$V_O = 0.5V$
I_{OZH}	3-STATE Output Leakage Current	3.6			5	μA	$V_O = 3.0V$
I_{OZH^+}	3-STATE Output Leakage Current	3.6			10	μA	$V_{CC} < V_O \leq 5.5V$
I_{CCH}	Power Supply Current	3.6			0.19	mA	Outputs HIGH
I_{CCL}	Power Supply Current	3.6			5	mA	Outputs LOW
I_{CCZ}	Power Supply Current	3.6			0.19	mA	Outputs Disabled
I_{CCZ^+}	Power Supply Current	3.6			0.19	mA	$V_{CC} \leq V_O \leq 5.5V$ Outputs Disabled
ΔI_{CC}	Increase in Power Supply Current (Note 7)	3.6			0.2	mA	One Input at $V_{CC} - 0.6V$ Other Inputs at V_{CC} or GND

Note 4: All typical values are at $V_{CC} = 3.3V$, $T_A = 25^\circ C$.

Note 5: An external driver must source at least the specified current to switch from LOW-to-HIGH.

Note 6: An external driver must sink at least the specified current to switch from HIGH-to-LOW.

Note 7: This is the increase in supply current for each input that is at the specified voltage level rather than V_{CC} or GND.

Dynamic Switching Characteristics (Note 8)

Symbol	Parameter	V_{CC} (V)	$T_A = 25^\circ C$			Units	Conditions $C_L = 50 \text{ pF}$, $R_L = 500\Omega$
			Min	Typ	Max		
V_{OLP}	Quiet Output Maximum Dynamic V_{OL}	3.3		0.8		V	(Note 9)
V_{OLV}	Quiet Output Minimum Dynamic V_{OL}	3.3		-0.8		V	(Note 9)

Note 8: Characterized in SOIC package. Guaranteed parameter, but not tested.

Note 9: Max number of outputs defined as (n). n-1 data inputs are driven 0V to 3V. Output under test held LOW.

AC Electrical Characteristics

Symbol	Parameter	$T_A = -40^\circ\text{C to } +85^\circ\text{C}$ $C_L = 50 \text{ pF}, R_L = 500\Omega$					Units	
		$V_{CC} = 3.3V \pm 0.3V$			$V_{CC} = 2.7V$			
		Min	Typ (Note 10)	Max	Min	Max		
t_{PLH}	Propagation Delay Data to Output	1.0		3.5	1.0	4.5	ns	
t_{PHL}		1.0		3.9	1.0	4.9		
t_{PZH}	Output Enable Time	1.0		4.0	1.0	5.5	ns	
t_{PZL}		1.1		4.0	1.1	5.4		
t_{PHZ}	Output Disable Time	1.5		4.5	1.5	5.7	ns	
t_{PLZ}		1.3		4.5	1.3	4.0		
t_{OSHL}	Output to Output Skew (Note 11)			1.0		1.0	ns	
t_{OSLH}								

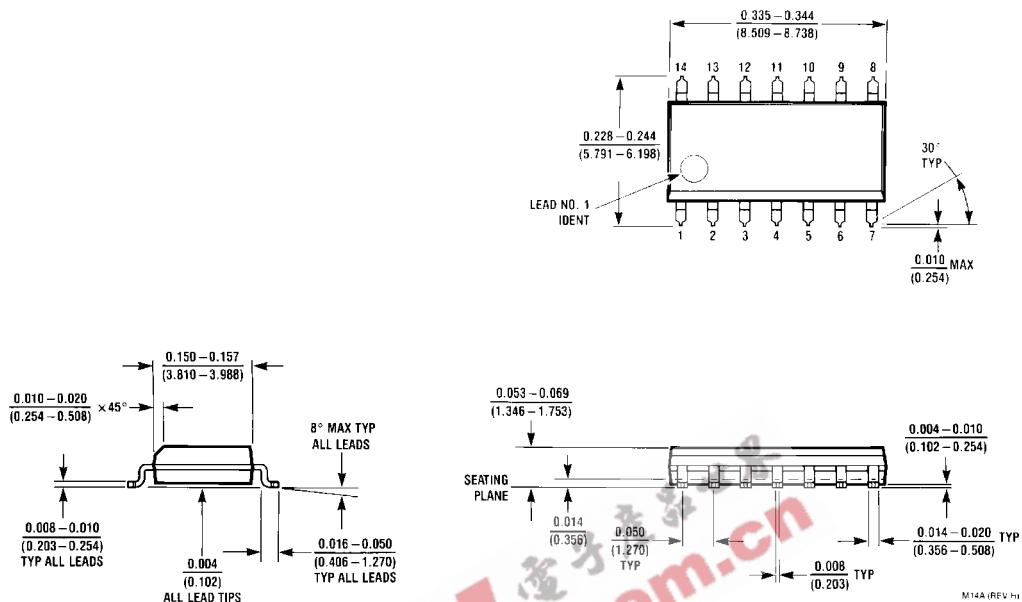
Note 10: All typical values are at $V_{CC} = 3.3V$, $T_A = 25^\circ\text{C}$.

Note 11: Skew is defined as the absolute value of the difference between the actual propagation delay for any two separate outputs of the same device. The specification applies to any outputs switching in the same direction, either HIGH-to-LOW (t_{OSHL}) or LOW-to-HIGH (t_{OSLH}).

Capacitance (Note 12)

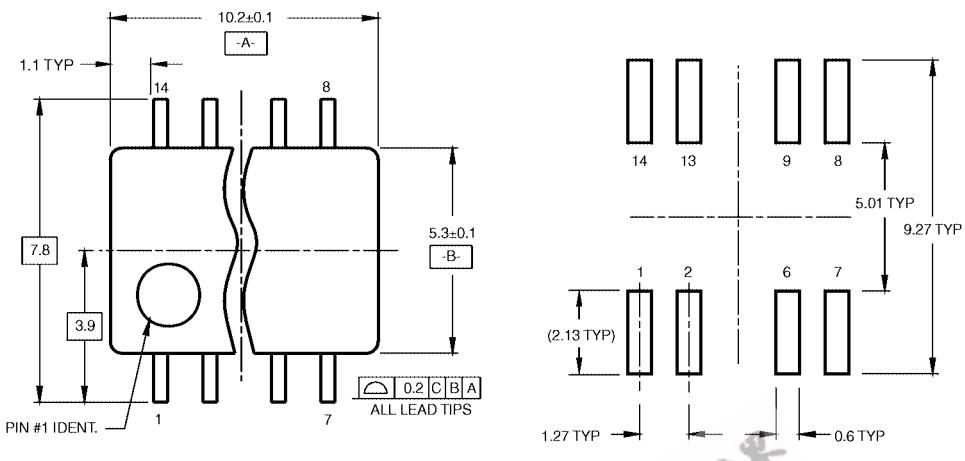
Symbol	Parameter	Conditions	Typical	Units
C_{IN}	Input Capacitance	$V_{CC} = 0V, V_I = 0V$ or V_{CC}	4	pF
C_{OUT}	Output Capacitance	$V_{CC} = 3.0V, V_O = 0V$ or V_{CC}	8	pF

Note 12: Capacitance is measured at frequency $f = 1 \text{ MHz}$, per MIL-STD-883B, Method 3012.

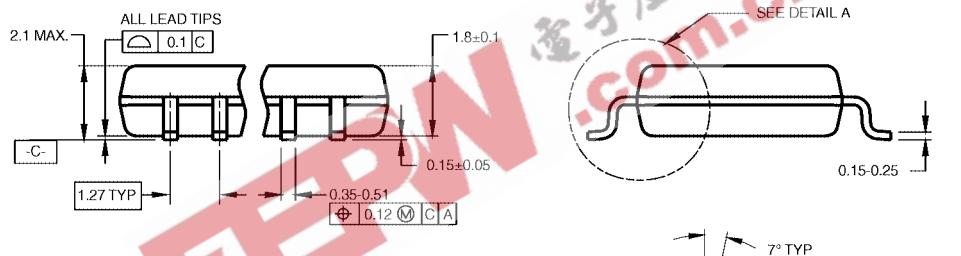
Physical Dimensions inches (millimeters) unless otherwise noted

14-Lead Small Outline Integrated Circuit (SOIC), JEDEC MS-012, 0.150" Narrow
Package Number M14A

Physical Dimensions inches (millimeters) unless otherwise noted (Continued)



LAND PATTERN RECOMMENDATION

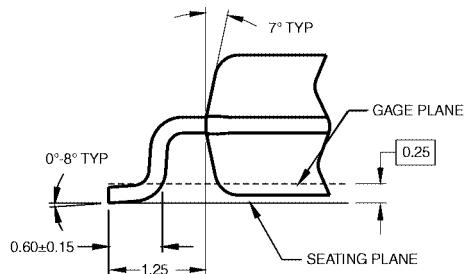


DIMENSIONS ARE IN MILLIMETERS

NOTES:

- A. CONFORMS TO EIAJ EDR-7320 REGISTRATION, ESTABLISHED IN DECEMBER, 1998.
- B. DIMENSIONS ARE IN MILLIMETERS.
- C. DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH, AND TIE BAR EXTRUSIONS.

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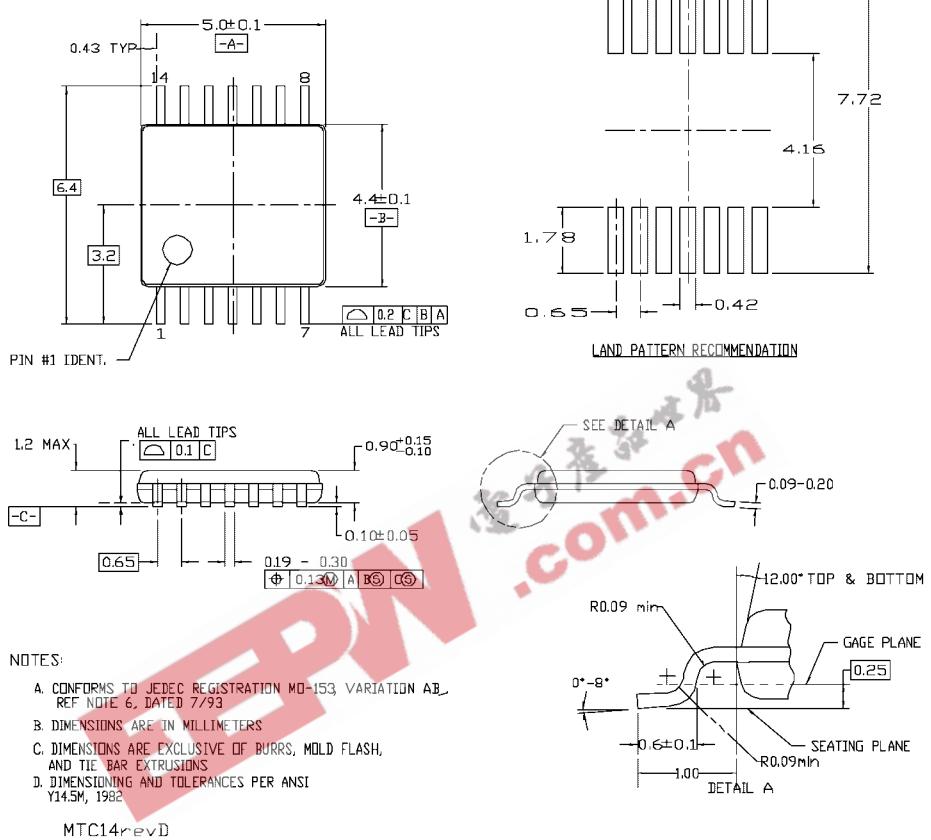


DETAIL A

Pb-Free 14-Lead Small Outline Package (SOP), EIAJ TYPE II, 5.3mm Wide
Package Number M14D

74LVTH125 Low Voltage Quad Buffer with 3-STATE Outputs

Physical Dimensions inches (millimeters) unless otherwise noted (Continued)



**14-Lead Thin Shrink Small Outline Package (TSSOP), JEDEC MO-153, 4.4mm Wide
Package Number MTC14**

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